



Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from,Europe,America and south Asia,supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of “Quality Parts,Customers Priority,Honest Operation,and Considerate Service”,our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



Contact us

Tel: +86-755-8981 8866 Fax: +86-755-8427 6832

Email & Skype: info@chipsmall.com Web: www.chipsmall.com

Address: A1208, Overseas Decoration Building, #122 Zhenhua RD., Futian, Shenzhen, China



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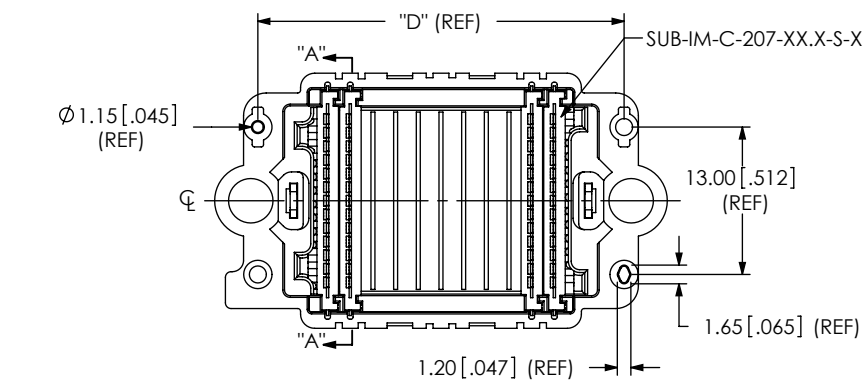
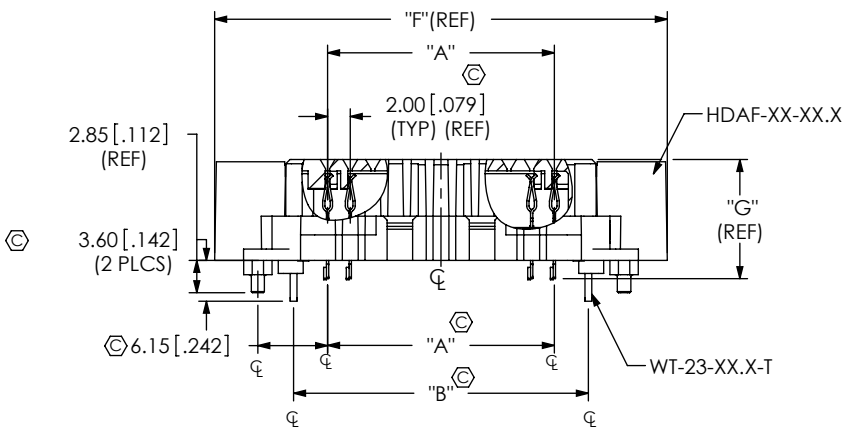
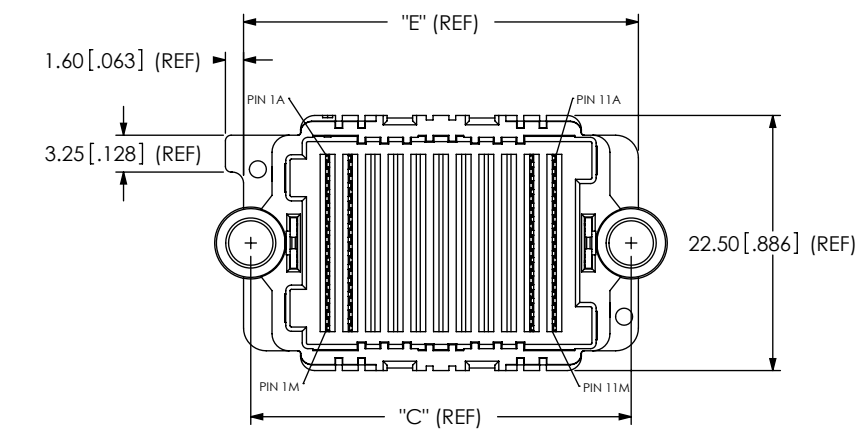


FIG 1
-11: 1T POSITION
(HDAF-11-08.0-X-13-X-X SHOWN)
(SOME WAFERS NOT SHOWN FOR CLARITY)

**DESIGNED & DIMENSIONED
IN MILLIMETERS
(INCHES FOR REFERENCE ONLY)**

- NOTES:
1. Ⓢ REPRESENTS A CRITICAL DIMENSION.
 2. MINIMUM PUSHOUT FORCE: 2.22N [.5 LB]. FOR WAFERS AND WELD TABS.
 3. CONNECTORS TO BE PACKAGED IN TRAYS.
 4. DIMENSION FROM ϕ OF END TAIL TO ϕ OF -A PIN.

HDAF-XX-XX.X-X-13-X-X

No OF POSITIONS (13 ROWS PER POSITION)
-11
-15
-23

LEAD STYLE
-08.0: 8MM
-18.0: 18MM

PLATING SPECIFICATION
-S: SELECTIVE, .000030 INCHES GOLD IN MATING AREA, MATTE TIN ON TAIL AND WELD TABS

OPTION
-P: PICK & PLACE PAD (USE MPP-26-01-N)

SOLDER CHARGE MATERIAL Ⓢ
-1: 63% TIN / 37% LEAD
-2: 95.5% TIN / 3.8% SILVER 0.7% COPPER (LEAD FREE)

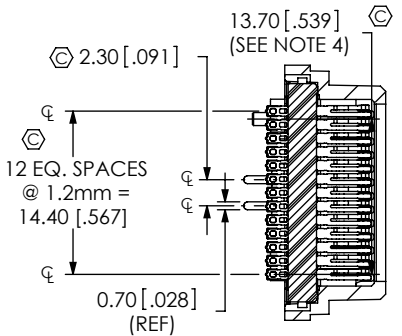
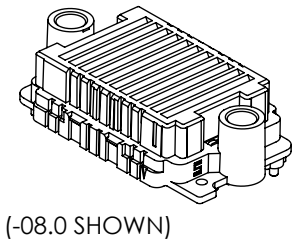
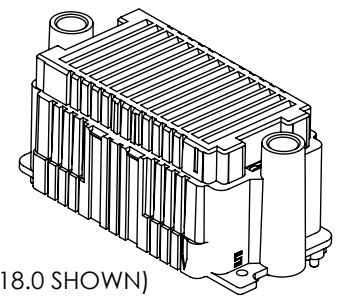
No OF ROWS
-13

TABLE 1

STYLE	"BODY CALLOUT"	"CONTACT WAFER"	"SOLDER NAIL"
-08.0	HDAF-XX-08.0	SUB-IM-C-207-08.0-S-X	WT-23-08.0-T
-18.0	HDAF-XX-18.0	SUB-IM-C-207-18.0-S-X	WT-23-18.0-T

**TABLE 2
STACK HEIGHT**

HDAF LEAD STYLE	HDAM LEAD STYLE	
	-12.0	-17.0
-08.0	20.0MM	25.0MM
-18.0	30.0MM	35.0MM



SECTION "A"-"A"

<p>UNLESS OTHERWISE SPECIFIED, DIMENSIONS ARE IN MILLIMETERS [INCHES]. TOLERANCES ARE: DECIMALS ANGLES X: +0.3 [.01] 2° XX: ±0.13 [.005] XXX: ±0.051 [.0020]</p>	<p>PROPRIETARY NOTE THIS DOCUMENT CONTAINS INFORMATION CONFIDENTIAL AND PROPRIETARY TO SAMTEC, INC. AND SHALL NOT BE REPRODUCED OR TRANSFERRED TO OTHER DOCUMENTS OR DISCLOSED TO OTHERS OR USED FOR ANY PURPOSE OTHER THAN THAT WHICH IT WAS OBTAINED WITHOUT THE EXPRESSED WRITTEN CONSENT OF SAMTEC, INC.</p>	<p>samtec 520 PARK EAST BLVD, NEW ALBANY, IN 47150 PHONE: 812-944-6733 FAX: 812-948-5047 e-Mail: info@SAMTEC.com code: 55322</p>
<p>MATERIAL: DO NOT SCALE DRAWING INSULATOR: LCP COLOR: BLACK CONTACT: COPPER ALLOY WAFER MATERIAL: LCP, COLOR: BLACK PICK AND PLACE PAD: COPPER ALLOY WELD TAB: BRASS</p>	<p>SHEET SCALE: 1:5:1</p>	<p>DESCRIPTION: 2.0MM PITCH HD ARRAY SOCKET ASSEMBLY DWG. NO. HDAF-XX-XX.X-X-13-X-X BY: D KNOWLDEN 7/14/2005 SHEET 1 OF 2</p>

TABLE 3								
No. OF POS.	LEAD STYLE	"A"	"B"	"C"	"D"	"E"	"F"	"G"
11	08.0	20.0 [1.787]	26.0 [1.02]	33.55 [1.321]	32.30 [1.272]	34.82 [1.371]	39.92 [1.572]	10.51 [1.414]
15	08.0	28.0 [1.102]	34.0 [1.34]	41.55 [1.636]	40.30 [1.587]	42.82 [1.686]	47.92 [1.887]	10.51 [1.414]
23	08.0	44.0 [1.732]	50.0 [1.97]	57.55 [2.266]	56.30 [2.217]	58.82 [2.316]	63.92 [2.517]	10.51 [1.414]
11	18.0	20.0 [1.787]	26.0 [1.02]	33.55 [1.321]	32.30 [1.272]	34.82 [1.371]	39.92 [1.572]	20.51 [1.807]
15	18.0	28.0 [1.102]	34.0 [1.34]	41.55 [1.636]	40.30 [1.587]	42.82 [1.686]	47.92 [1.887]	20.51 [1.807]
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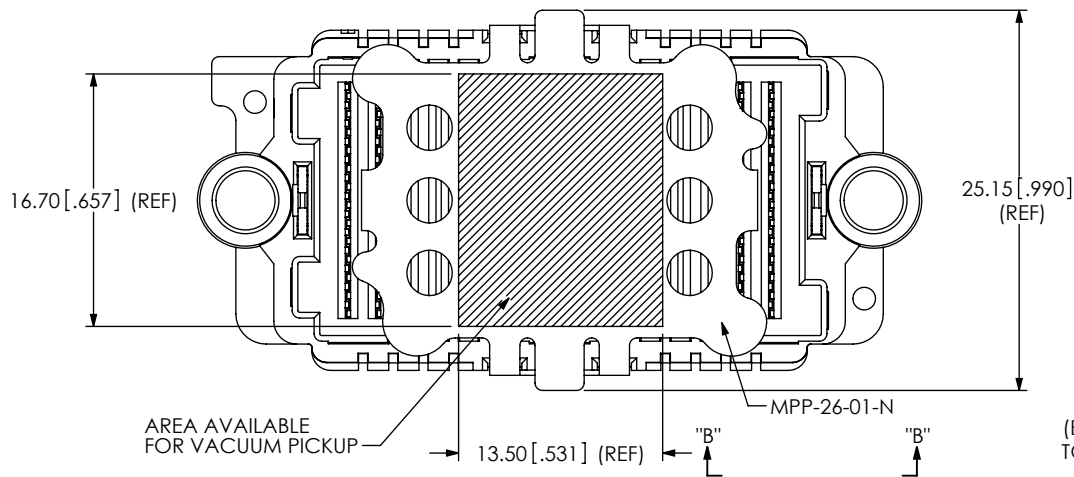
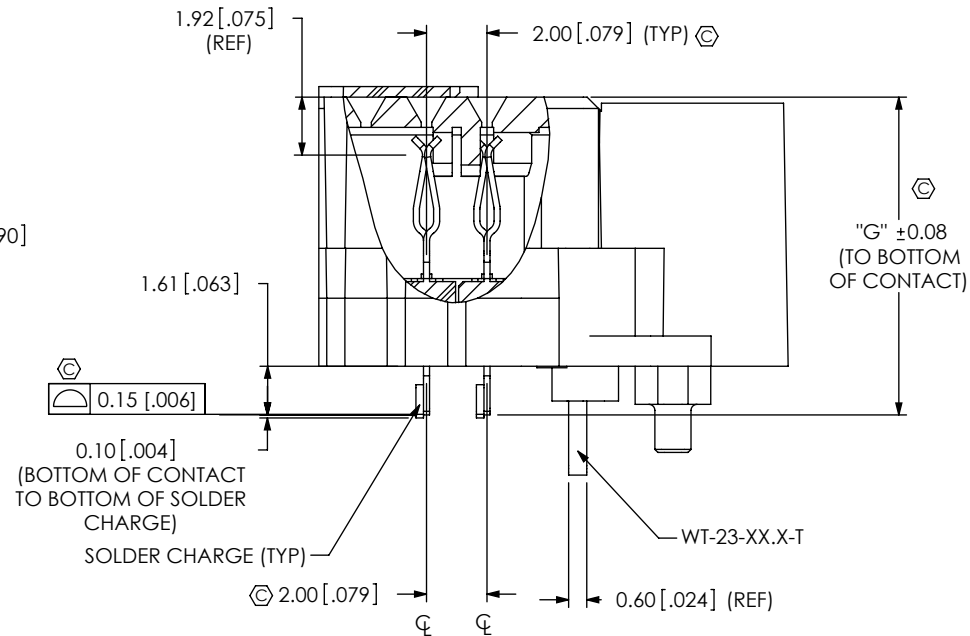
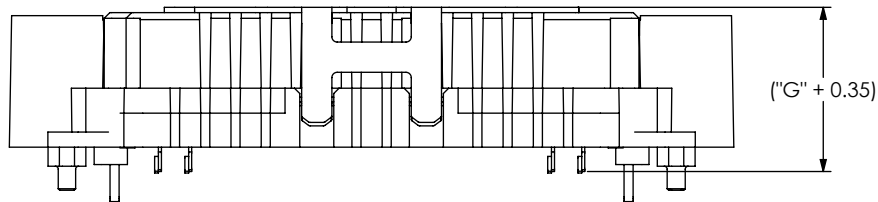


FIG 2
-15: 15 POSITION
(HDAF-15-08.0-X-13-X-P SHOWN)
(SOME WAFERS NOT SHOWN FOR CLARITY)



VIEW "B"-"B"
SCALE 4:1

F:\DWG\MISC\MKTG\HDAF-XX-XX.X-X-13-X-X-MKT.SLDDRW

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SHEET SCALE: 1:1

samtec

520 PARK EAST BLVD, NEW ALBANY, IN 47150
PHONE: 812-944-6733 FAX: 812-948-5047
e-Mail: info@SAMTEC.com code: 55322

DESCRIPTION:
2.0MM PITCH HD ARRAY SOCKET ASSEMBLY

DWG. NO.
HDAF-XX-XX.X-X-13-X-X

BY:D KNOWLDEN 7/14/2005 SHEET 2 OF 2